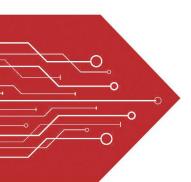
MSKSEMI















ESD

TVS

TSS

MOV

GDT

PLED

Broduct data sheet

Semiconductor

Compiance

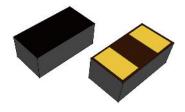
Features

- Ultra-Low capacitance:0.05pF(typ.)
- Low leakage current(<10nA)
- Fast response time(<1ns)
- Bi-directional,single line protection
- IEC 61000-4-2 (ESD Air): 15kV IEC 61000-4-2 (ESD Contact): 8kV

Applications

- USB 3.0/3.1
- HDMI 1.3/1.4/2.0
- RF Antenna
- SATA and eSATA Interface

Pin Description



Schematic Diagram



Order Information

Туре	Package	Size (mm)	Delivery Form	Delivery Quantity
MSPESD06DMA12	0603	1.60x0.80x0.40	7" T&R	5,000

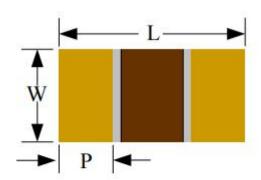
Limiting Values(T_A = 25 °C, unless otherwise specified)

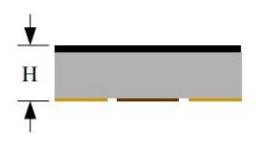
Symbol	Parameter	Conditions		Max	Unit
	El ((); B: V()	IEC 61000-4-2; Contact Discharge		8	kV
V _{ESD}	Electrostatic Discharge Voltage	IEC 61000-4-2; Air Discharge	-	15	kV
T _A	Operating Temperature Range	-	-55	125	°C
T _{stg}	Storage Temperature Range	-	-40	85	°C

Electrical Characteristics(T_A = 25 °C unless otherwise specified)

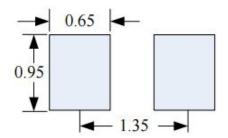
Symbol	Parameter	Conditions	Min	Тур.	Max	Unit
V _{DC}	Continuous Operating Voltage	-	-	-	12.0	V
V _T	Trigger Voltage	IEC61000-4-2 8kV contact	-	450	-	V
		discharge				
Vc	Clamping Voltage	IEC61000-4-2 8kV contact	-	40	-	V
		discharge				
lι	Leakage Current	DC 12V shall be applied	1	-	10	nA
		on component				
CJ	Capacitance	Measured at 10MHz	-	0.05	-	pF

Package Dimension





Recommended Solder Pad Footprint



*Sizes in mm

Notes:

This solder pad layout is for reference purposes only.

Dimension	Unit: Millimeters		
	Min.	Max.	
L	1.45	1.75	
W	0.70	0.95	
Р	0.20	0.50	
Н	0.26	0.46	



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